

Gallium Nitride 28V, 5W, DC-1500MHz MMIC PA

Built using the SIGANTIC® NRF1 process - A proprietary GaN-on-Silicon technology

FEATURES

- Optimized for broadband operation from DC-1500-MHz
- Input and output matched to 50 Ohms
- > 38dBm saturated power up to 1000MHz
- · High small signal gain
 - 22dB @ 200MHz
 - 18dB @ 1000MHz
- · Low noise figure
 - 1.8dB @ 200MHz
 - 2.5dB @ 1000MHz



4mm x 4mm
QFN Package
With Exposed Pad



Subject to EAR99 export control

RF Specifications (CW, DC-1000MHz): $V_{DS} = 28V$, $I_{DQ} = 100$ mA, $T_A = 25$ °C, Measured in Nitronex 50 Ohm test fixture.

Symbol	Parameter	Min	Тур	Max	Units
G _{SS}	Small-signal Gain	17.5	19.0	-	dB
P _{SAT}	Saturated Output Power	36.5	38	-	dBm
G _P	Gain at P _{SAT}	13	14.5	-	dB
η	Drain Efficiency at P _{SAT}	35	45	-	%
	Gain Flatness at P _{SAT}	-	+/- 3.5	-	dB
	Harmonics at P _{OUT} = 36dBm	-	-20	-	dBc
NF	Noise Figure	-	2.5		
OIP3	Output IP3, 1MHz spacing, 32dBm/tone	-	47	-	dBm
IRL	Input Return Loss	-	-8	-	dB
ORL	Output Return Loss	-	-15	-	dB

NPA1003 Preliminary Datasheet



DC Specifications: $T_C = 25^{\circ}C$

Symbol	ymbol Parameter		Тур	Max	Units
Off Characteristics					^
V _{BDS}	Drain-Source Breakdown Voltage (V _{GS} = -8V, I _D = 2mA)	100	-	-	V
I _{DLK}	Drain-Source Leakage Current (V _{GS} = -8V, V _{DS} = 60V)		0.5	1.0	mA
On Characteristics					,
V _T	Gate Threshold Voltage (V _{DS} = 28V, I _D = 2mA)	-2.1	-1.6	-1.1	V
V_{GSQ}	Gate Quiescent Voltage (V _{DS} = 28V, I _D = 100mA)	-1.7	-1.2	-0.7	V
R _{ON}	R_{ON} On Resistance $(V_{GS} = 2V, I_D = 15mA)$		2.0	-	Ω
I _{D,MAX}	Drain Current $(V_{DS} = 7V \text{ pulsed}, 300 \mu \text{s pulse width}, 0.2\% \text{ duty cycle}, V_{GS} = 2.0V)$	1.1	1.4	-	А

Thermal Resistance Specification

Symbol	Parameter	Min	Тур	Max	Units
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case), $T_J = 180 ^{\circ}\text{C}$	1	12.0	1	°C/W

Absolute Maximum Ratings: Not simultaneous, T_C = 25°C unless otherwise noted

Symbol	Parameter	Max	Units
V _{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	-10 to 3	V
I_{G}	Gate Current	10	mA
P _T	Total Device Power Dissipation (Derated above 25°C)	14.5	W
T _{STG}	Storage Temperature Range	-65 to 150	°C
T_J	Operating Junction Temperature	200	°C
HBM	Human Body Model ESD Rating (per JESD22-A114)	TBD	
MM	Machine Model ESD Rating (per JESD22-A115)	TBD	
MSL	Moisture sensitivity level (per IPC/JEDEC J-STD-020)	TBD	
P _{IN}	Maximum Input Power	TBD	

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RF Performance in 50 Ohm Test Fixture With External Bias Tee

 $V_{DS} = 28V$, $I_{DQ} = 100$ mA, $T_A = 25$ °C,

CW signal unless otherwise noted, Reference plane: Connectors

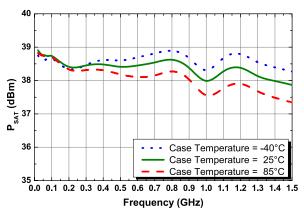


Figure 1 - Saturated Output Power vs Frequency

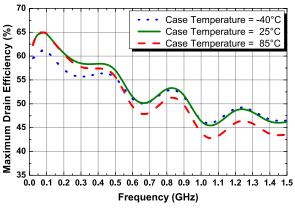


Figure 3 - Maximum Drain Efficiency vs Frequency

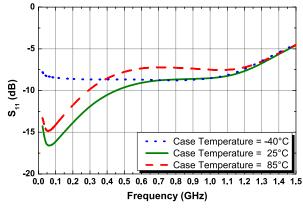


Figure 5 - Input Return Loss vs Frequency

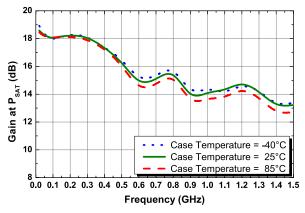


Figure 2 - Gain at Saturated Output Power vs Frequency

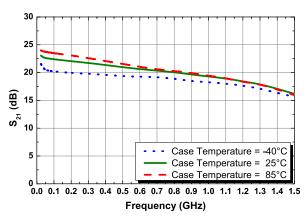


Figure 4 - Small-Signal Gain vs Frequency

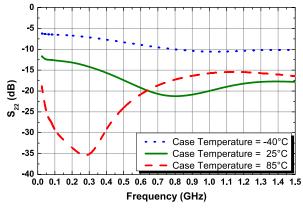


Figure 6 - Output Return Loss vs Frequency

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RF Performance in 50 Ohm Test Fixture With External Bias Tee

 $V_{DS} = 28V, I_{DO} = 100mA, T_A = 25^{\circ}C,$

CW signal unless otherwise noted, Reference plane: Connectors

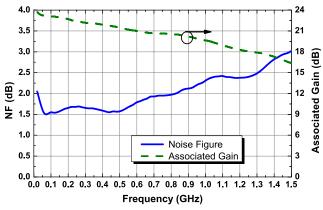
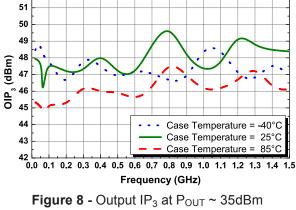


Figure 7 - Noise Figure vs Frequency



vs Frequency

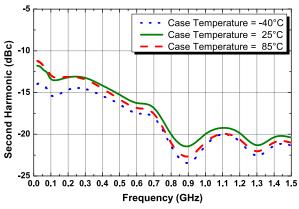


Figure 9 - Second Harmonic at Pout = 36dBm vs Frequency

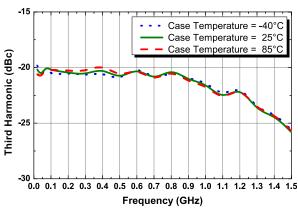


Figure 10 - Third Harmonic at Pout = 36dBm vs Frequency

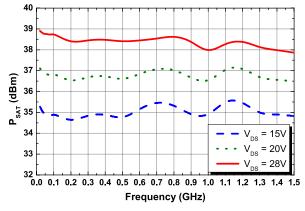


Figure 11 - Saturated Output Power vs V_{DS} and Frequency

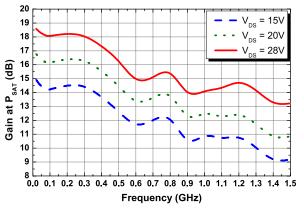


Figure 12 - Gain at Saturated Output Power vs V_{DS} and Frequency

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RF Performance in 50 Ohm Test Fixture With External Bias Tee

 $V_{DS} = 28V$, $I_{DQ} = 100$ mA, $T_A = 25$ °C,

CW signal unless otherwise noted, Reference plane: Connectors

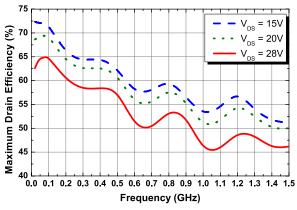


Figure 13 - Maximum Drain Efficiency vs V_{DS} and Frequency

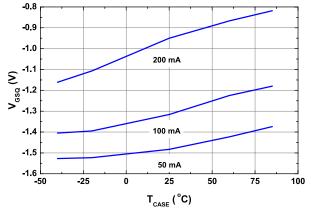


Figure 14 - Quiescent Gate Voltage (V_{GSQ}) Required to Reach I_{DQ} vs T_{CASE}

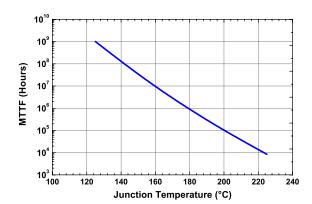


Figure 15 - MTTF of NRF1 Devices as a Function of Junction Temperature

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Ordering Information¹

Part Number	Order Multiple	Description
NPA1003QAT	92	Tube; NPA1003 in QA (4x4 QFN-16 lead with exposed pad) Package
NPA1003QAR	1500	Tape and Reel; NPA1003 in QA (4x4 QFN-16 lead with exposed pad) Package

^{1:} To find a Nitronex contact in your area, visit our website at http://www.nitronex.com

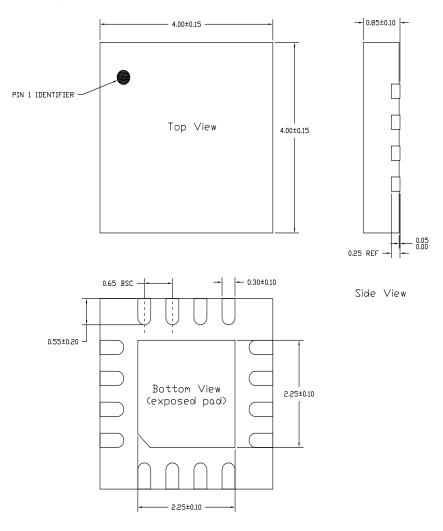


Figure 16 - QA Package Dimensions and Pinout (all dimensions are in millimeters)

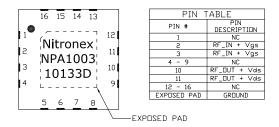


Figure 17 - Terminal Identification

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Additional Information

This part is lead-free and is compliant with the RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

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